Final Product Change Notification

201409001F01

Issue Date: 04-Sep-2014
Effective Date: 16-Dec-2014

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Management Summary

Wafer production for the display drivers PCF85176T (in TSSOP56) and PCF85162T (in TSSOP48) will move from TSMC to Vanguard (VIS). We also change the wire bonding material from gold to copper.

Change Category

[ ] Wafer Fab process
[ ] Wafer Fab materials
[X] Wafer Fab location
[X] Assembly Process
[X] Assembly Materials
[ ] Assembly Location
[X] Product Marking
[ ] Electrical spec./Test coverage
[ ] Test Location
[ ] Design
[ ] Mechanical Specification
[ ] Packing/Shipping/Labeling

PCF85176T and PCF85162T change the wafer fab and bond wire material

Details of this Change

Wafer production for the display drivers PCF85176T (in TSSOP56) and PCF85162T (in TSSOP48) will move from TSMC to Vanguard (VIS). The semiconductor process will remain the same. Also the specification will be unchanged except some minor changes in current consumption.
We also change the wire bonding material from gold (Au) to copper (Cu). There will be no effect in form or funcion related to this change.

Why do we Implement this Change

- To align with world technology trends
- To use wiring with enhanced mechanical and electrical properties
- To simplify the supply chain

Identification of Affected Products

- Third line of the product marking will change start with an "r" instead of an "k"

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 02-Dec-2014

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 04-Oct-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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